

EM-S526 / EM-S526B

Low Loss / Low CTE / Halogen Free

- Applications include: W/B, CSP, BGA, FC PKG, SiP, module and coreless.
- High heat resistance and excellent CAF resistance.
- Low Df for better signal integrity and flexible circuit design.
- Low CTE for anti-warpage solution of IC substrate.
- RoHS Compliant
- UL File: E150504
- Applicable IPC Slash Sheets: IPC-4103 /240, /540

Basic Laminate Property

Property	Item		Typical Value	Unit	Test Condition	IPC-TM-650
Thermal	Tg		N/A	°C	DSC	2.4.25
			230	°C	TMA	2.4.24
			260	°C	DMA	2.4.24.4
	CTE, X/Y-axis		9/10	ppm/°C	< Tg, TMA	2.4.24.5
	CTE, Z-axis		25~30	ppm/°C	< Tg, TMA	2.4.24
			120~140	ppm/°C	> Tg, TMA	
	Td		430	°C	TGA (5% W.L)	2.4.24.6
	T288		>60	min.	Clad	2.4.24.1
>60			min.	Etched		
Thermal Conductivity		0.60	W/m.K		ASTM D5470	
Electrical	Dk (R/C: 50/70%)	1 GHz	4.0/3.5	-	C-24/23/50	2.5.5.9
		10GHz	3.9/3.4	-		Cavity Resonator
	Df (R/C: 50/70%)	1 GHz	0.005/0.006	-	C-24/23/50	2.5.5.9
		10GHz	0.007/0.008	-		Cavity Resonator
	Volume Resistivity		>10 ¹⁰	MΩ-cm	C-96/35/90	2.5.17.1
Surface Resistivity		>10 ⁹	MΩ	C-96/35/90	2.5.17.1	
Physical	Water Absorption		0.12	%	E-1/105+D-24/23	2.6.2.1
	Peel Strength	VLP, 12 um	0.9	kg/cm	As Received	2.4.8
	Flexural Modulus	Warp	24~26	GPa	As Received	2.4.4
		Fill	23~25	GPa	As Received	
Flame Resistance		V-0	-	A & E-24/125	UL-94	

Above typical values are tested under specified constructions and not intended for specification.